Copper Layer Count: 2 Board Thickness: 1.6000 mm

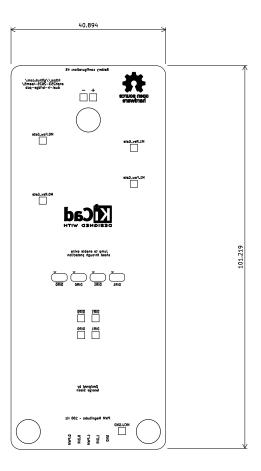
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Sleen			
Team 5			
Sheet:			
File: dual-h-	-bridge.kicad_pcb		
Title: Dual	l H–Bridge		
Size: A4 Date: 2025-06-19 Rev: A			
KiCad E.D.A. 9.0.2		ld: 1/4	

Copper Layer Count: 2 Board Thickness: 1.6000 mm

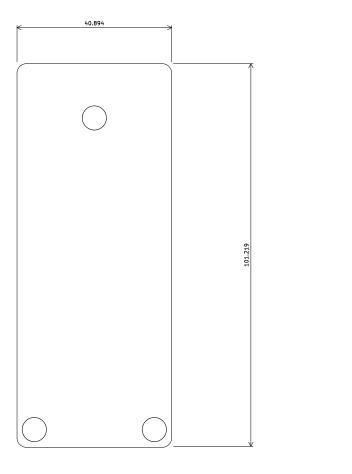
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

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F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



Copper Layer Count: 2 Board Thickness: 1.6000 mm

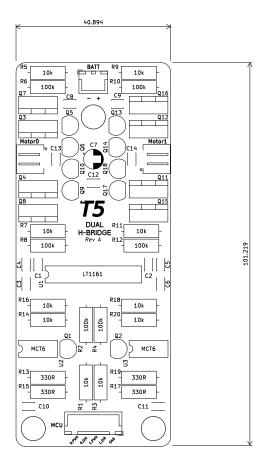
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

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F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Sleen					
Team 5					
Sheet:	Sheet:				
File: dual-h-bridge.kicad_pcb					
Title: Dual H	l–Bridge		1		
Size: A4	Rev: A	٦			
KiCad E.D.A. 9.0.	2	ld: 3/4	1		
/1	5	i'	_,		

Copper Layer Count: 2 Board Thickness: 1.6000 mm

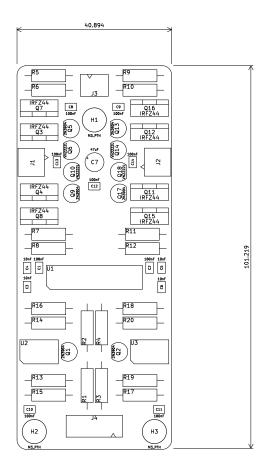
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

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B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Sleen						
Team 5						
Sheet:						
File: dual-h-bri	File: dual-h-bridge.kicad_pcb					
Title: Dual H-Bridge						
Size: A4	Size: A4 Date: 2025-06-19 Rev: A					
KiCad E.D.A. 9.0	KiCad E.D.A. 9.0.2					